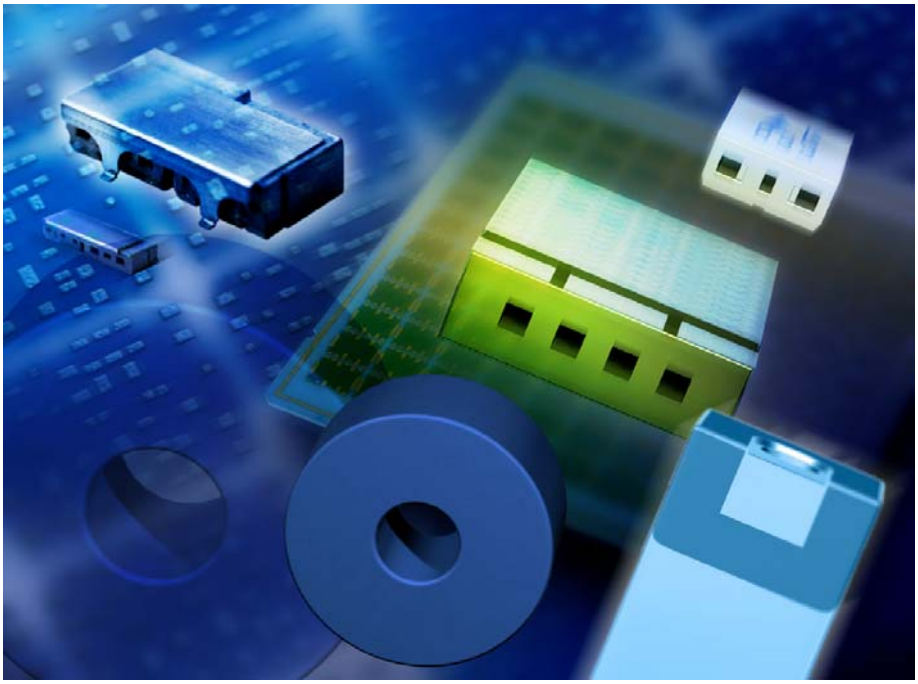
2-Pole Filter for W-LAN B69812N2457A301

Data Sheet



Features

- SMD filter consisting of coupled resonators with stepped impedances
- extreme low losses
- high attenuations at GSM (900, 1800, 1900) bands
- stable performance over wide temperature range
- excellent reflow solderability, no migration effect due to copper/tin metallization

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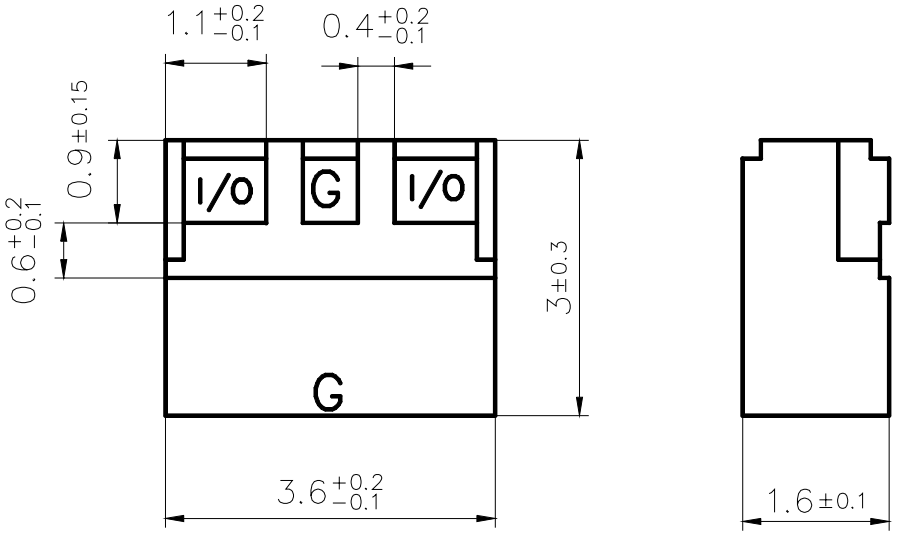
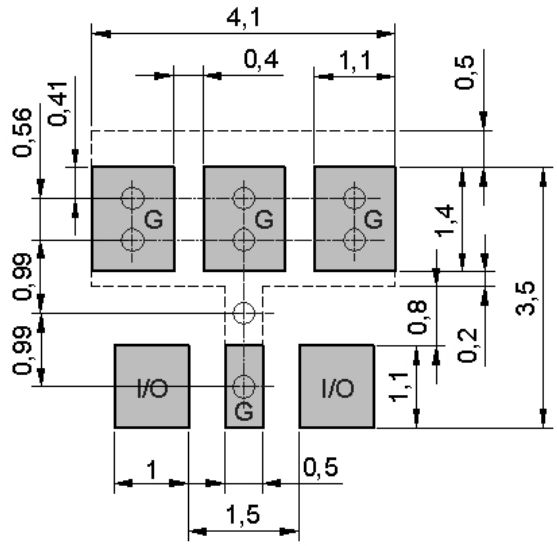
Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint



Top view and marking

Y : year
WW : week

soldered areas

I/O Pads must be terminated with 50 Ω characteristic impedance

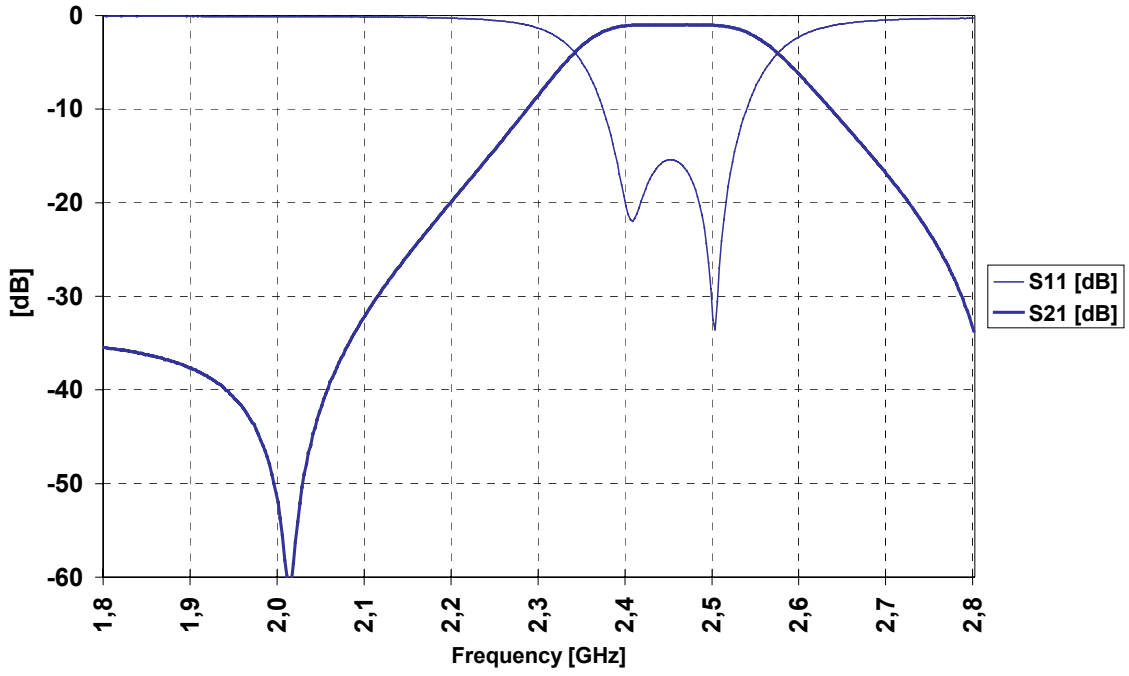
Characteristics over whole temperature range

		min.	typ.	max.	
Center frequency	f_C	-	2.4415	-	GHz
Insertion loss (2400 – 2483MHz)	α_{IL}		0.8	1.2	dB
Passband	B	83			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.4	0.8	dB
Standing wave ratio	SWR		1.5	2.0	
Impedance (2400 – 2483MHz)	Z		50		Ω
Attenuation	α				
at DC to 960 MHz		42	46		dB
at 960 to 1990 MHz		32	35		dB
at 2100 to 2170 MHz		20	23		dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	- 40 / + 85	°C

Typical passband characteristic



Processing information

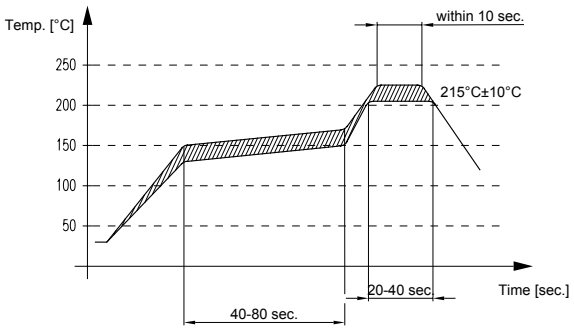
ZNr.: 527 (FILT95_2)

- Wettability acc. to IEC 68-2-58: ≥ 75% (after aging)

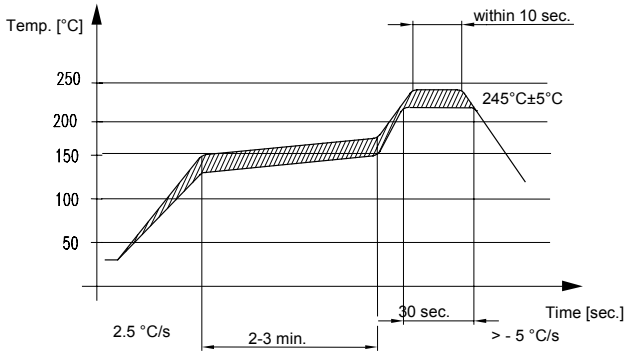
Soldering requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



eutectic SnPb solder paste profile



leadfree solder paste profile

Delivery mode

- Blister tape acc. to IEC 286-3, polystyrol, grey
- Pieces/tape: 3000